



# SOT97-2

plastic dual in-line package; 8 leads (300 mil)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DIP8
<b>Package type industry code</b>	DIP8
<b>Package style descriptive code</b>	DIP (dual in-line package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	- - -
<b>JEDEC package outline code</b>	MO-001
<b>JEITA package outline code</b>	- - -
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	18-10-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.2	-	9.5	9.8	mm
E	package width	6.2	-	6.34	6.48	mm
A	seated height	[tbd]	-	[tbd]	4.2	mm
A <sub>2</sub>	package height	[tbd]	-	[tbd]	3.43	mm
e	nominal pitch	-	-	2.54	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	



## 2. Package outline

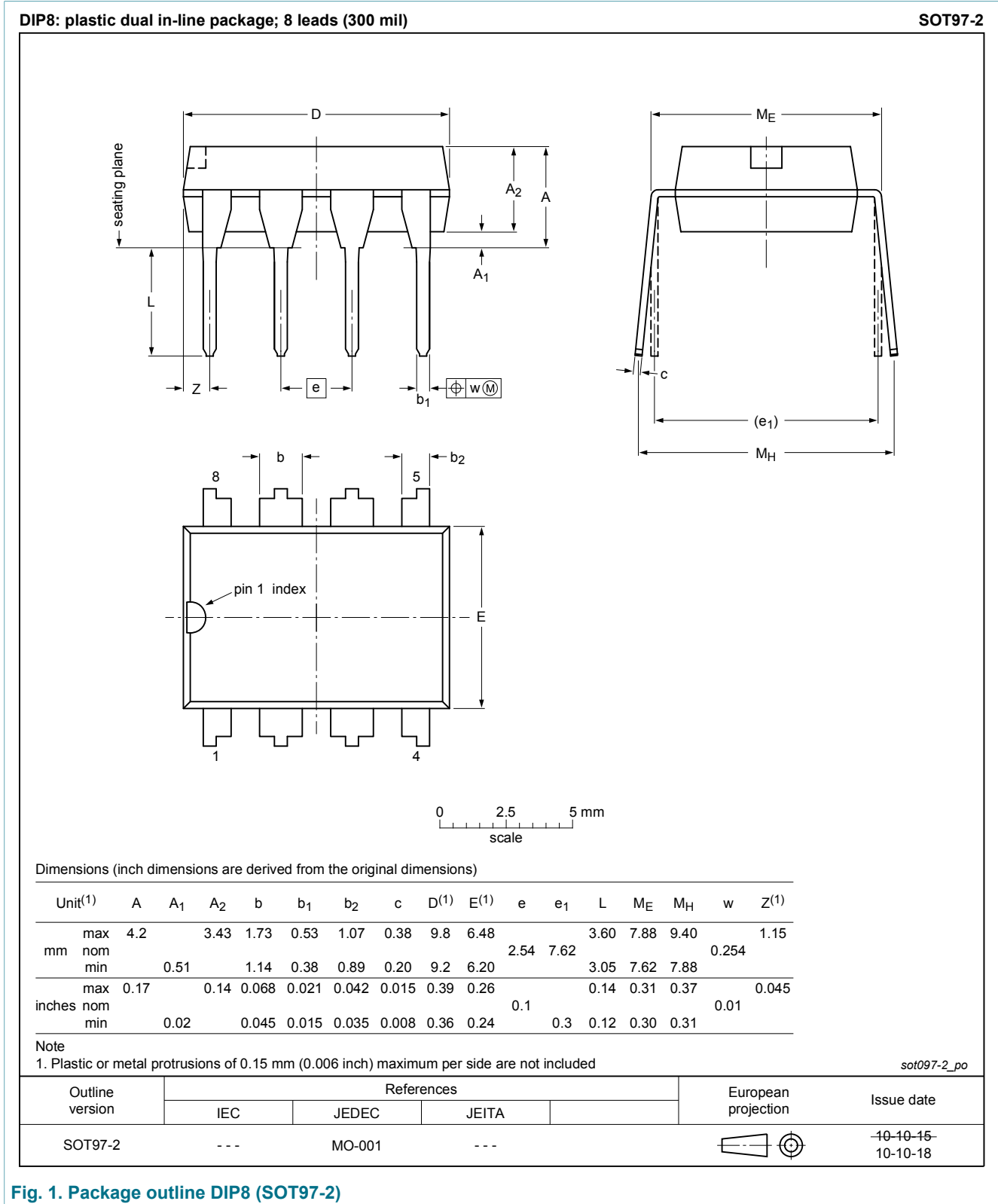


Fig. 1. Package outline DIP8 (SOT97-2)

### 3. Legal information

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